



Material Content Data Sheet



Sales Product Name				IPD200N15N3 G		Issued		1. August 2018	
MA#				MA001280870					
Package				PG-TO252-3-313		Weight*		321.49 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	6.312	1.96	1.96	19634	19634	
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		137		
	non noble metal	iron	7439-89-6	0.147	0.05		458		
	non noble metal	copper	7440-50-8	147.096	45.76	45.82	457551	458146	
	non noble metal	aluminium	7429-90-5	4.219	1.31	1.31	13125	13125	
wire	non noble metal	aluminium	7429-90-5	4.219	1.31	1.31	13125	13125	
encapsulation	organic material	carbon black	1333-86-4	1.343	0.42		4178		
	plastics	epoxy resin	-	23.503	7.31		73109		
	inorganic material	silicondioxide	60676-86-0	109.458	34.05	41.78	340477	417764	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.16	1.16	11634	11634	
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11		
	non noble metal	nickel	7440-02-0	1.421	0.44	0.44	4419	4430	
solder	non noble metal	tin	7440-31-5	0.100	0.03		311		
	noble metal	silver	7440-22-4	0.125	0.04		388		
	non noble metal	lead	7439-92-1	4.770	1.48	1.55	14837	15536	
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	iron	7439-89-6	0.019	0.01		60		
	non noble metal	copper	7440-50-8	19.177	5.97	5.98	59653	59731	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com